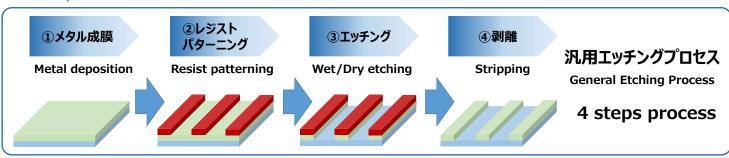
電子部品・半導体デバイス用フォトレジスト

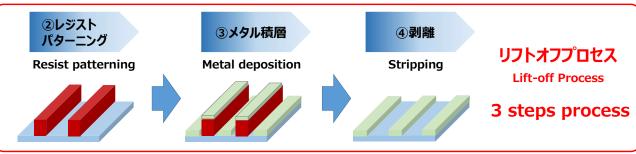
Photoresist for Electronic Components and Semiconductor Devices



リフトオフプロセス

Lift-off Process



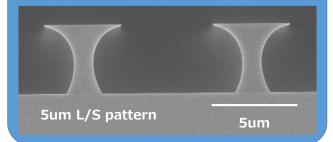




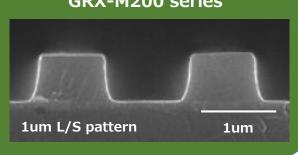
製品ラインナップ

Production Lineup

リフトオフプロセス用単層レジスト Single layer type of resist for lift-off process NPR9700 series

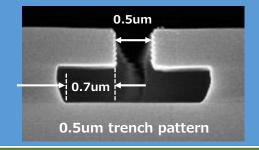


フォトマスク製造用レジスト Photoresist for production of photomask GRX-M200 series

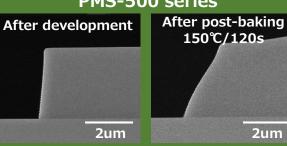


リフトオフプロセス用2層レジスト

Double layer type of resist for lift-off process BLX-200 series



パワーモジュール製造用レジスト
Photoresist for production of power module
PMS-500 series





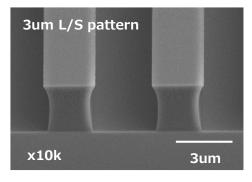
リフトオフプロセス用 単層&2層レジスト

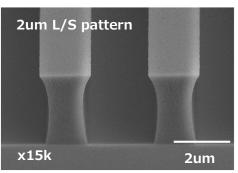
Single/Double Layer Type of Resist for Lift-off Process

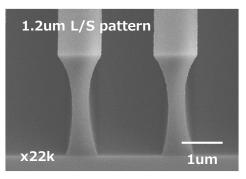


リフトオフプロセス用単層レジスト NPR9730

Single layer type of resist for lift-off process







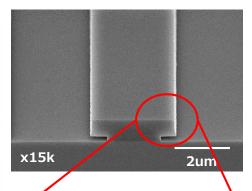
少しラフなメタル分割用途で、短いタクトタイムでの生産用途に適しています。

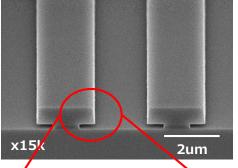
NPR9730 is suitable for producing the rough divided metal lines. It's an effective selection for making tact time shorter of your production line to apply our NPR9730.

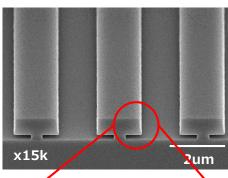


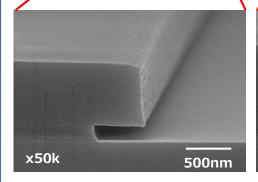
リフトオフプロセス用2層レジスト BLX-210

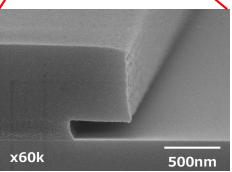
Double layer type of resist for lift-off process

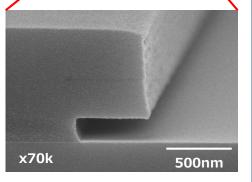












タクトタイムは長くなりますが、微細なメタル分割が必要な生産用途に適しています。

The tact time of this process is longer than single layer lift-off process. Double layer process can make fine divided metal lines without the dry etcher machine.

Please feel free to ask below contact any questions.

